

MATERIAL:
 Housing: LCP, 94V-0, Black
 Contact: Copper Alloy
 Latch: Stainless Steel; 50u" Nickel Subplate; 100u" Matte Tin Overall
 Contact Plating: Specified Au thickness in Contact area; Au Flash on remaining area ;50u" min Nickel subplate

Recommended Stencil Thickness : 0.12 min.
 Reflow Compatible : 260 C max for 10 sec.

MECHANICAL:
 Insertion Force: 59.8 N max.
 Durability: 25 Cycles
 Shock: Pass EIA -364-27
 Vibration: Pass EIA -364-28

ELECTRICAL:
 Current Rating : 0.5 A
 Voltage Rating : 1.1 V
 Contact Resistance: 40 milliohms initial; 20 milliohm max change
 Insulation Resistance : 1 Megaohm min at 500V DC
 Dielectric Withstanding Voltage: 250 VAC min for 1 minute

ENVIRONMENTAL:
 Operating Temperature: -55 C to 85 C
 Solderability: Pass JESD22-B102 C
 Humidity : Pass EIA 364-21
 Thermal Shock :EIA-364-32, Method A, Table 2 Test Condition 1
 Salt Spray : 48 H

HOW TO ORDER:

B 0 3 0 - 2 6 2 5 - 7 0 X 1 - Z HF

NUMBER OF CONTACTS:
262

HEIGHT OPTION:
7 - 8.0mm

ORIENTATION:
0 - Standard

KEY TYPE / VOLTAGE OPTION:
5 - 1.1 Volt

PLATING:

- 2 - Full Au Flash
- 5 - 10µ" Au
- 6 - 15µ" Au
- 8 - 30µ" Au

RoHS COMPLIANT

PACKAGING:

- 0 - Tray
- 1 - Tape & Reel (Normal)
- 2 - Tape & Reel (Reverse)

HALOGEN FREE

Rev	Drawn	Checked	Approved	Date
0	B.S.	S.M.	S.M.	06/24/25

SMP TECHNOLOGY, INC.

DDR 5 SO DIMM Socket, 262 Position, 1.1Volt,
 Standard Orientation, 8.0mm Height,

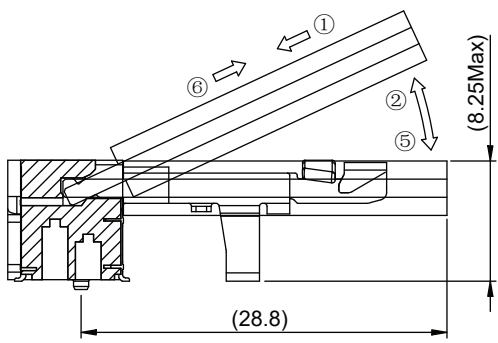
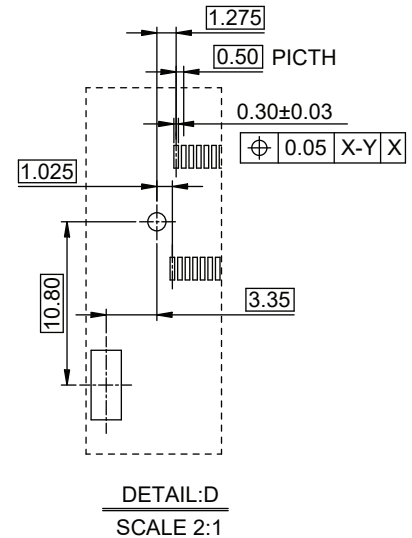
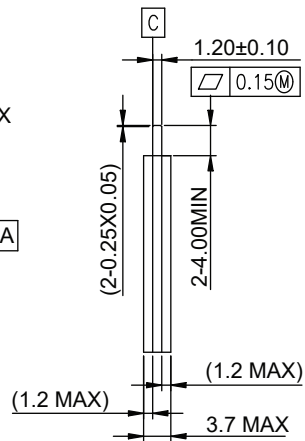
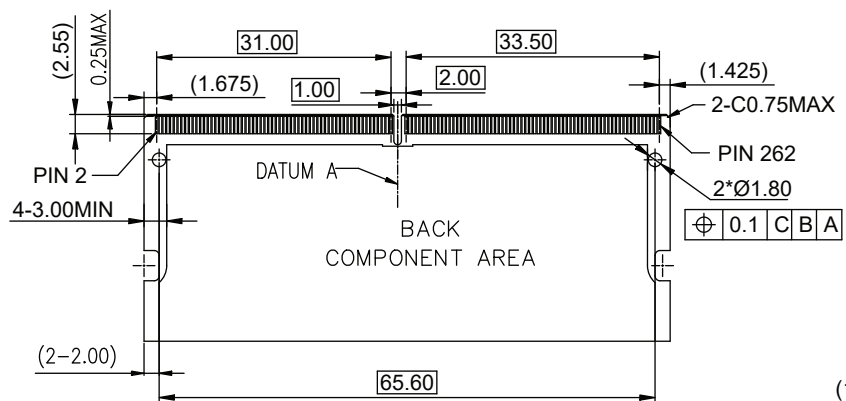
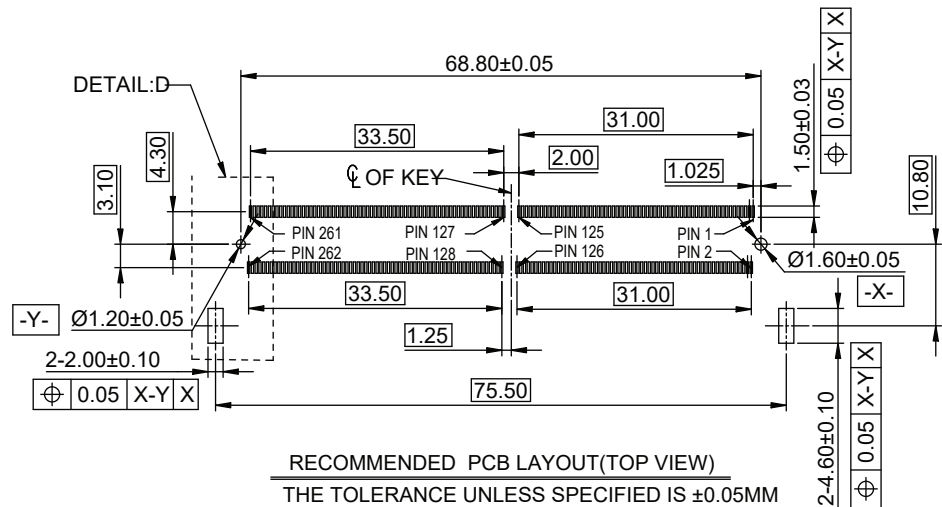
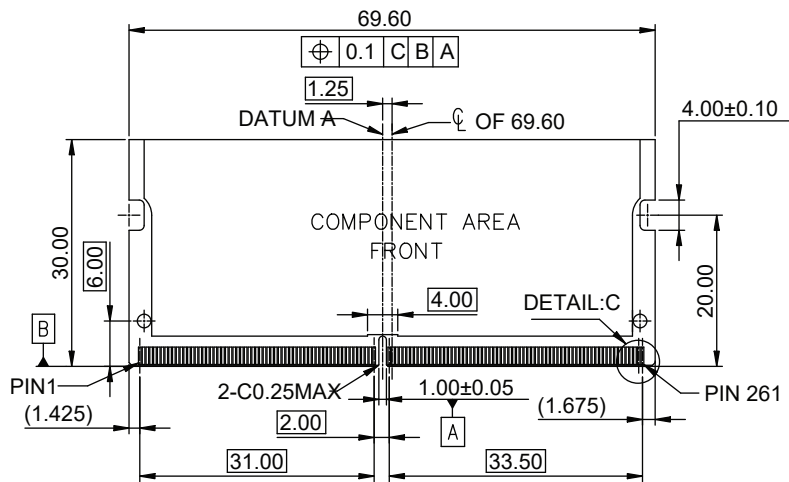
TOL. DEC. X +/- 0.30 .X +/- 0.25 .XX +/- 0.20

ANGLE +/- 3°

UNIT: mm

P/N: B030-2625-70X1-ZHF

Pg: 1 of 3



MATING:① INSERTING(25°) → ② ROTATING → ③ FIXED
UNMATING:④ UNFIXED → ⑤ ROTATING → ⑥ WITHDRAWING

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DDR 5 SO DIMM Socket, 262 Position, 1.1Volt,
Standard Orientation, 8.0mm Height,

